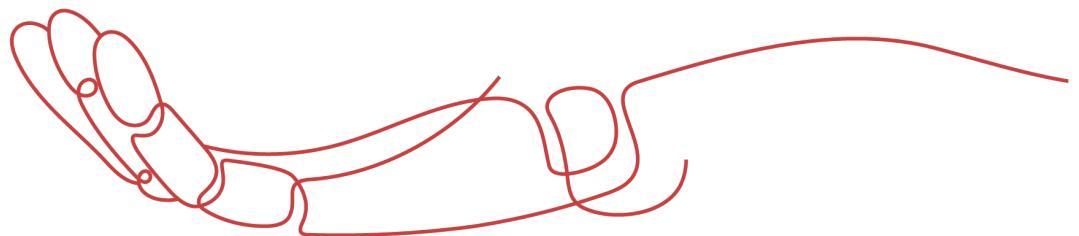


## PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at

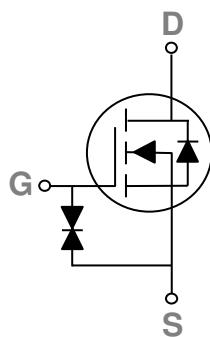
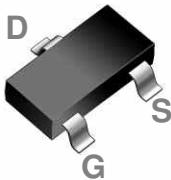


Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT-23 Pin Configuration



BVDSS	RDSON	ID
60V	2.2Ω	0.3A

### Features

- 60V, 0.3A,  $RDS(ON) = 2.2\Omega$  @  $VGS = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available
- G-S ESD Protection Diode Embedded
- ESD protected up to 2KV

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c = 25^\circ C$ )	0.3	A
	Drain Current – Continuous ( $T_c = 100^\circ C$ )	0.1	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	0.8	A
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	0.35	W
	Power Dissipation – Derate above $25^\circ C$	0.003	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	357	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±10	uA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =0.3A	---	2.2	2.8	Ω
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.2A	---	2.4	3.0	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	1.6	2.5	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =0.3A	---	0.5	---	S

**Dynamic and switching Characteristics**

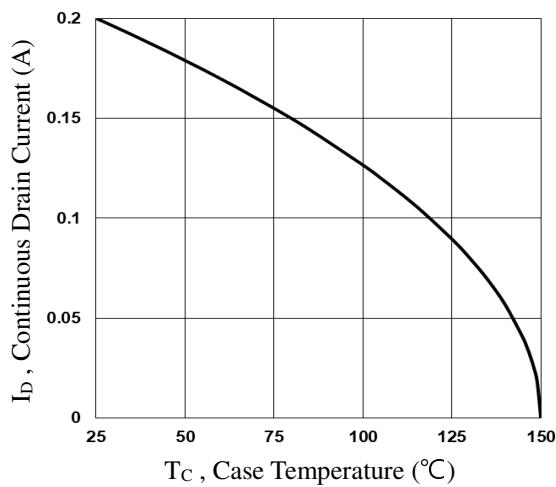
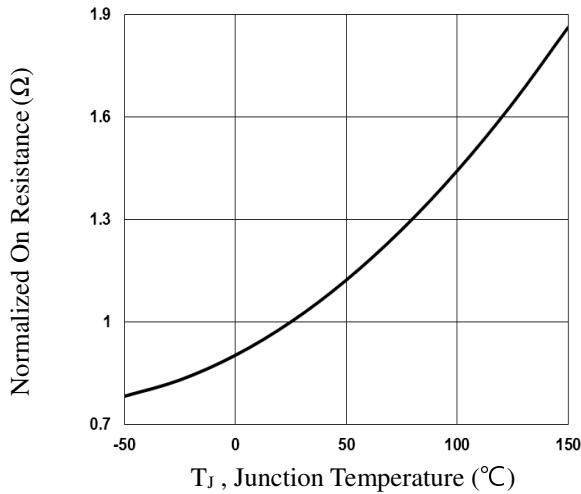
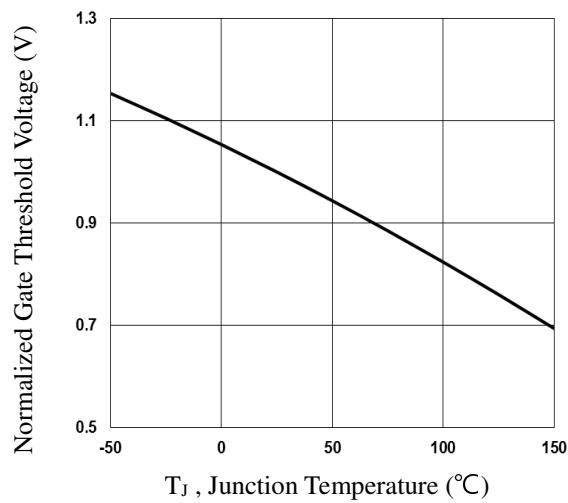
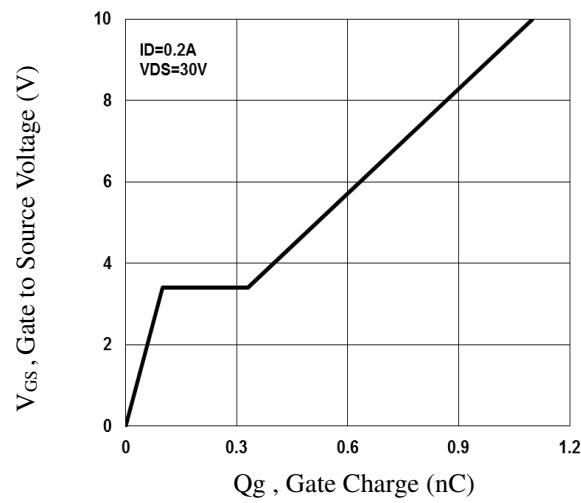
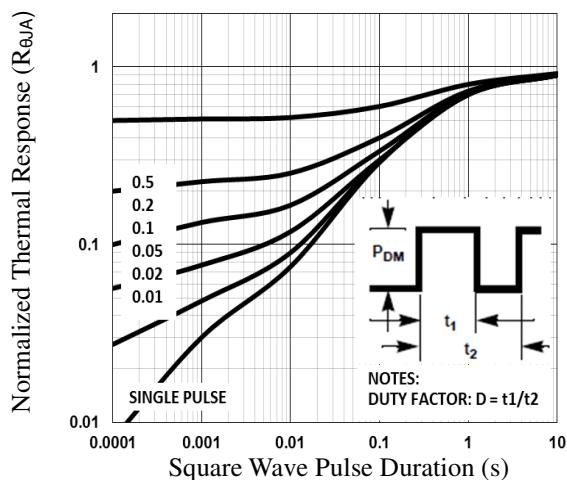
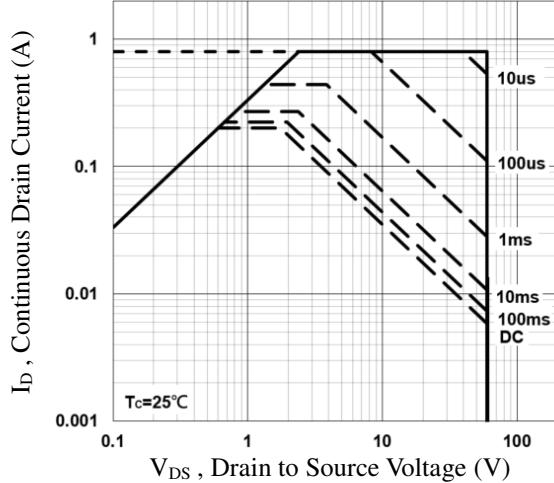
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =1A	---	3.7	---	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	0.9	---	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	0.4	---	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =0.2A	---	3	---	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	5	---	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	14	---	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	9	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1MHz	---	25.5	---	pF
C <sub>oss</sub>	Output Capacitance		---	17	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	7.8	---	

**Drain-Source Diode Characteristics and Maximum Ratings**

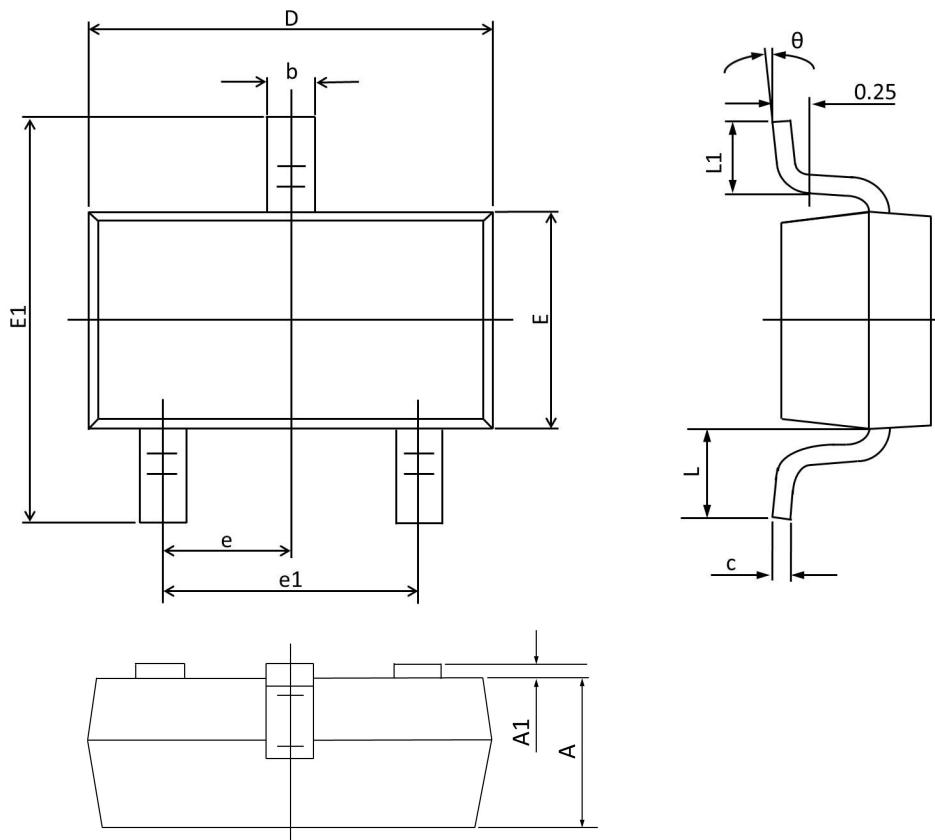
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	0.3	A
			---	---	1.2	A
I <sub>SM</sub>	Pulsed Source Current	V <sub>GS</sub> =0V, I <sub>s</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
			---	---	1	V
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =50V, I <sub>s</sub> =1A, dI/dt=100A/μs	---	3.4	---	ns
			---	0.7	---	nC
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	---	---	---
			---	---	---	---

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TC**

**Fig.2 Normalized RDS(on) vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**

## SOT-23 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°

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